Notice for TAIYO YUDEN products

Please read this notice before using the TAIYO YUDEN products.

REMINDERS

Product Information in this Catalog

Product information in this catalog is as of January 2021. All of the contents specified herein and production status of the products listed in this catalog are subject to change without notice due to technical improvement of our products, etc. Therefore, please check for the latest information carefully before practical application or use of our products.

Please note that TAIYO YUDEN shall not be in any way responsible for any damages and defects in products or equipment incorporating our products, which are caused under the conditions other than those specified in this catalog or individual product specification sheets.

Approval of Product Specifications

Please contact TAIYO YUDEN for further details of product specifications as the individual product specification sheets are available. When using our products, please be sure to approve our product specifications or make a written agreement on the product specification with TAIYO YUDEN in advance.

Pre-Evaluation in the Actual Equipment and Conditions

Please conduct validation and verification of our products in actual conditions of mounting and operating environment before using our products.

Limited Application

1. Equipment Intended for Use

The products listed in this catalog are intended for generalpurpose and standard use in general electronic equipment (e.g., AV equipment, OA equipment, home electric appliances, office equipment, information and communication equipment including, without limitation, mobile phone, and PC) and other equipment specified in this catalog or the individual product specification sheets.

TAIYO YUDEN has the line-up of the products intended for use in automotive electronic equipment, telecommunications infrastructure and industrial equipment, or medical devices classified as GHTF Classes A to C (Japan Classes I to III). Therefore, when using our products for these equipment, please check available applications specified in this catalog or the individual product specification sheets and use the corresponding products.

2. Equipment Requiring Inquiry

Please be sure to contact TAIYO YUDEN for further information before using the products listed in this catalog for the following equipment (excluding intended equipment as specified in this catalog or the individual product specification sheets) which may cause loss of human life, bodily injury, serious property damage and/or serious public impact due to a failure or defect of the products and/or malfunction attributed thereto.

- (1) Transportation equipment (automotive powertrain control system, train control system, and ship control system, etc.)
- (2) Traffic signal equipment
- (3) Disaster prevention equipment, crime prevention equipment
- (4) Medical devices classified as GHTF Class C (Japan Class III)
- (5) Highly public information network equipment, dataprocessing equipment (telephone exchange, and base station, etc.)
- (6) Any other equipment requiring high levels of quality and/or reliability equal to the equipment listed above

3. Equipment Prohibited for Use

Please do not incorporate our products into the following equipment requiring extremely high levels of safety and/or reliability.

- (1) Aerospace equipment (artificial satellite, rocket, etc.)
- (2) Aviation equipment *1
- (3) Medical devices classified as GHTF Class D (Japan Class IV), implantable medical devices *²

- (4) Power generation control equipment (nuclear power, hydroelectric power, thermal power plant control system, etc.)
- (5) Undersea equipment (submarine repeating equipment, underwater work equipment, etc.)
- (6) Military equipment
- (7) Any other equipment requiring extremely high levels of safety and/or reliability equal to the equipment listed above

*Notes:

- There is a possibility that our products can be used only for aviation equipment that does not directly affect the safe operation of aircraft (e.g., in-flight entertainment, cabin light, electric seat, cooking equipment) if such use meets requirements specified separately by TAIYO YUDEN. Please be sure to contact TAIYO YUDEN for further information before using our products for such aviation equipment.
- Implantable medical devices contain not only internal unit which is implanted in a body, but also external unit which is connected to the internal unit.

4. Limitation of Liability

Please note that unless you obtain prior written consent of TAIYO YUDEN, TAIYO YUDEN shall not be in any way responsible for any damages incurred by you or third parties arising from use of the products listed in this catalog for any equipment that is not intended for use by TAIYO YUDEN, or any equipment requiring inquiry to TAIYO YUDEN or prohibited for use by TAIYO YUDEN as described above.

Safety Design

When using our products for high safety and/or reliability-required equipment or circuits, please fully perform safety and/or reliability evaluation. In addition, please install (i) systems equipped with a protection circuit and a protection device and/or (ii) systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault for a failsafe design to ensure safety.

Intellectual Property Rights

Information contained in this catalog is intended to convey examples of typical performances and/or applications of our products and is not intended to make any warranty with respect to the intellectual property rights or any other related rights of TAIYO YUDEN or any third parties nor grant any license under such rights.

Limited Warranty

Please note that the scope of warranty for our products is limited to the delivered our products themselves and TAIYO YUDEN shall not be in any way responsible for any damages resulting from a failure or defect in our products. Notwithstanding the foregoing, if there is a written agreement (e.g., supply and purchase agreement, quality assurance agreement) signed by TAIYO YUDEN and your company, TAIYO YUDEN will warrant our products in accordance with such agreement.

TAIYO YUDEN's Official Sales Channel

The contents of this catalog are applicable to our products which are purchased from our sales offices or authorized distributors (hereinafter "TAIYO YUDEN's official sales channel"). Please note that the contents of this catalog are not applicable to our products purchased from any seller other than TAIYO YUDEN's official sales channel.

Caution for Export

Some of our products listed in this catalog may require specific procedures for export according to "U.S. Export Administration Regulations", "Foreign Exchange and Foreign Trade Control Law" of Japan, and other applicable regulations. Should you have any questions on this matter, please contact our sales staff.

for General Electronic Equipment

METAL CORE WIRE-WOUND CHIP POWER INDUCTORS (MCOIL™ MA-H SERIES)

| | | | * Operating T | emp.:-40~+125°C(I | ncluding self-ge | nerated heat |) | REFLOW |
|----------------|---------------------|------------------------------------|------------------------------|------------------------|------------------|---------------|---------|-----------------|
| PARTS NUMB | ER | | | emp.:-40~+105°C(I | | | | umber reference |
| MAK 12 | K 2 0 1 | 6 H 1 R 4 5 | 0 M () (| ∆=Blank | k space | | | |
| ①Series name | | | | ⑤Nominal inductand | ce | | | |
| Code | | eries name vound Chip Power Ind | uctor | Code (example) | Nomir | al inductance | e[μH] | |
| | | | | R47 | | 0.47 | | |
| ②Dimensions(T) |) | | | 1R0 | | 1.0 | | |
| Code | Dimen | sions(T)[mm] | | 4R7 | | 4.7 | | |
| KK | | 1.0 | | ℜR=Decimal point | | | | |
| MK | | 1.2 | | | | | | |
| | | | | 6 Inductance tolera | nce | | | |
| ③Dimensions(L) | ×W) | | | Code | Indu | uctance toler | ance | |
| Code | Type(inch) | Dimension (L×W)[mi | | М | | ±20% | | |
| 2016 | 2016(0806) | 2.0 × 1.6 | | ⑦Special code | | | | |
| 2520 | 2520(1008) | 2.5 × 2.0 | | Code | Special code | | | |
| | | · | | Δ Standard | | | | |
| ④Packaging | | | | | | | | |
| Code | Packaging or | Special specification | | Internal code | | | | |
| H | Taping(Hig | gh characteristics) | | | | | | |
| | | | | | | | | |
| STANDARD E | XTERNAL DIMENSION | NS / STANDARD QU | | 1 18.0 | | | | |
| . L | w | | Recommended Surface Mount | Land Patterns | | | | |
| + | | * | | soldering conditions | should be chec | ked beforeba | nd | |
| T | | | | Idering process to the | | | | |
| · | | - | | | Туре | A | B | С |
| | |) | | | 2016 | 0.7 | 0.8 | 1.8 |
| | | | | ↓ − | 2520 | 0.8 | 1.2 | 2.0 |
| | | | KA K B | | | | | Unit:mm |
| Туре | L | W | Т | e | : | Standard quai | | |
| | 2.0±0.1 | 1.6±0.1 | 1.0 max | 0.5±0.3 | | Tapir | 18 | |
| MAKK2016H | (0.079 ± 0.004) | (0.063 ± 0.004) | (0.039 max) | (0.020 ± 0.012) | | 3000 |) | |
| MAKK2520H | 2.5±0.2 | 2.0±0.2 | 1.0 max | 0.5 ± 0.3 | | 3000 | <u></u> | |
| | (0.098±0.008) | (0.079±0.008) | (0.039 max) | (0.020 ± 0.012) | | 3000 | , | |
| MAMK2520H | 2.5±0.2 | 2.0±0.2 | 1.2 max | 0.5 ± 0.3 | | 3000 |) | |
| | (0.098 ± 0.008) | (0.079 ± 0.008) | (0.047 max) | (0.020 ± 0.012) | | 0000 | - | |

This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our product specification sheets. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our website (http://www.ty-top.com/).

POWER INDUCTORS

Unit:mm(inch)

| MAKK2016H(080 | 06) type | Thickness: 1.0mm | max. | | |
|---------------|----------|-------------------------|----------------------|--|--|
| Parts number | EHS | Nominal inductance [| Inductance tolerance | Self-resonant frequency [MHz] (min.) | |

| | | Manager 1 for dealers and | | Self-resonant | DC Resistance | | ※)[mA](max.) | Measuring | |
|---------------|------------------------|---------------------------|----------------------|--------------------------|---------------|----------------------------|----------------------------------|----------------|--|
| Parts number | EHS Nominal inductance | | Inductance tolerance | frequency [MHz](min.) | [Ω] (max.) | Saturation current Idc1 | Temperature rise current Idc2 | frequency[MHz] | |
| MAKK2016HR22M | RoHS | 0.22 | ±20% | - | 0.026 | 5,800 | 4,000 | 2 | |
| MAKK2016HR24M | RoHS | 0.24 | ±20% | - | 0.026 | 5,800 | 4,000 | 2 | |
| MAKK2016HR33M | RoHS | 0.33 | ±20% | - | 0.030 | 4,700 | 3,500 | 2 | |
| MAKK2016HR47M | RoHS | 0.47 | ±20% | - | 0.036 | 4,300 | 3,300 | 2 | |
| MAKK2016HR68M | RoHS | 0.68 | ±20% | - | 0.050 | 3,200 | 2,700 | 2 | |
| MAKK2016H1R0M | RoHS | 1.0 | ±20% | - | 0.070 | 2,700 | 2,300 | 2 | |
| MAKK2016H1R5M | RoHS | 1.5 | ±20% | - | 0.105 | 2,100 | 1,800 | 2 | |

Rated current ※) [mA](max.)

MAKK2520H(1008) type [Thickness: 1.0mm max.]

| | | Newinel industry of | | Self-resonant | DC Resistance | Rated current ※) [mA](max.) | | Measuring |
|--|------|---|------|---------------|----------------------------|----------------------------------|----------------|-----------|
| Parts number EHS Nominal inductance [μ H] | | Inductance tolerance frequency [MHz] (min | | [Ω] (max.) | Saturation current Idc1 | Temperature rise current Idc2 | frequency[MHz] | |
| MAKK2520HR22M | RoHS | 0.22 | ±20% | - | 0.021 | 7500 | 4900 | 2 |
| MAKK2520HR33M | RoHS | 0.33 | ±20% | - | 0.026 | 6200 | 4300 | 2 |
| MAKK2520HR47M | RoHS | 0.47 | ±20% | - | 0.029 | 5700 | 4000 | 2 |
| MAKK2520HR68M | RoHS | 0.68 | ±20% | - | 0.043 | 4300 | 3400 | 2 |
| MAKK2520H1R0M | RoHS | 1.0 | ±20% | - | 0.053 | 3800 | 3000 | 2 |
| MAKK2520H1R5M | RoHS | 1.5 | ±20% | - | 0.078 | 3000 | 2400 | 2 |
| MAKK2520H2R2M | RoHS | 2.2 | ±20% | - | 0.120 | 2500 | 1800 | 2 |
| MAKK2520H100M ※1 | RoHS | 10 | ±20% | - | 0.650 | 1100 | 750 | 2 |

MAMK2520H(1008) type [Thickness:1.2mm max.]

| | | Number 1 in dust second | | Self-resonant | DC Resistance | Rated current | Manager | |
|---------------|------|----------------------------|----------------------|------------------------|---------------|----------------------------|----------------------------------|-----------------------------|
| Parts number | EHS | Nominal inductance [μΗ] | Inductance tolerance | frequency [MHz] (min.) | | Saturation current Idc1 | Temperature rise current Idc2 | Measuring frequency[MHz] |
| MAMK2520HR22M | RoHS | 0.22 | ±20% | - | 0.021 | 7500 | 5000 | 2 |
| MAMK2520HR33M | RoHS | 0.33 | ±20% | - | 0.023 | 6600 | 4400 | 2 |
| MAMK2520HR47M | RoHS | 0.47 | ±20% | - | 0.026 | 5800 | 4100 | 2 |
| MAMK2520HR68M | RoHS | 0.68 | ±20% | - | 0.036 | 5100 | 3500 | 2 |
| MAMK2520H1R0M | RoHS | 1.0 | ±20% | - | 0.045 | 4300 | 3100 | 2 |
| MAMK2520H1R5M | RoHS | 1.5 | ±20% | - | 0.065 | 3300 | 2600 | 2 |
| MAMK2520H2R2M | RoHS | 2.2 | ±20% | - | 0.090 | 2800 | 2200 | 2 |

%) The saturation current value (Idc1) is the DC current value having inductance decrease down to 30%. (at 20°C)

%) The temperature rise current value(Idc2) is the DC current value having temperature increase by 40°C. (at 20°C)

%) The rated current value is following either Idc1 or Idc2, which is the lower one.

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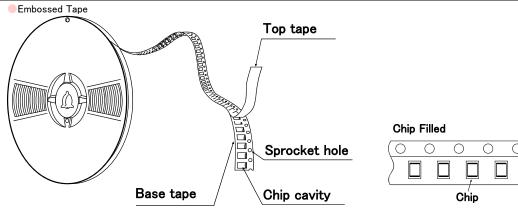
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METAL CORE WIRE-WOUND CHIP POWER INDUCTORS (MCOIL[™] MA SERIES / MCOIL[™] MA-H SERIES)

PACKAGING

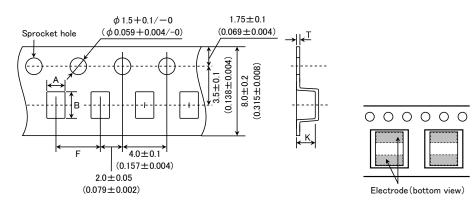
| ①Minimum Quantity | | | | | |
|-------------------|-------------------------|--|--|--|--|
| Turne | Standard Quantity [pcs] | | | | |
| Туре | Tape & Reel | | | | |
| MAKK2016 | 3000 | | | | |
| MAKK2520 | 3000 | | | | |
| MAMK2520 | 3000 | | | | |
| | | | | | |

2 Tape Material



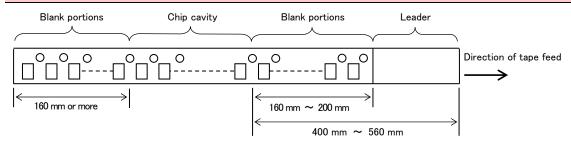
3Taping dimensions

Embossed tape 8mm wide (0.315 inches wide)



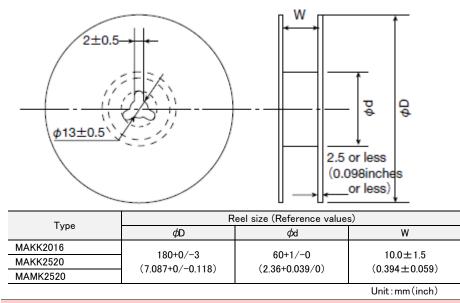
| Туре | Chip cavity | | Insertion pitch | Tape thickness | |
|----------|---------------------|---------------------|---------------------|---------------------|---------------|
| туре | A | В | F | Т | К |
| MAKK2016 | 1.9 ± 0.1 | 2.3±0.1 | 4.0±0.1 | 0.25 ± 0.05 | 1.2 max |
| WARKZUTU | (0.075 ± 0.004) | (0.091 ± 0.004) | (0.157 ± 0.004) | (0.009 ± 0.002) | (0.047 max) |
| MAKK2520 | 2.3±0.1 | 2.8±0.1 | 4.0±0.1 | 0.3 ± 0.05 | 1.25 max |
| MARRZJZU | (0.091 ± 0.004) | (0.110 ± 0.004) | (0.157 ± 0.004) | (0.012 ± 0.002) | (0.049 max) |
| MAMK2520 | 2.3±0.1 | 2.8±0.1 | 4.0±0.1 | 0.3 ± 0.05 | 1.4 max |
| | (0.091 ± 0.004) | (0.110 ± 0.004) | (0.157 ± 0.004) | (0.012 ± 0.002) | (0.055 max) |
| | | | | | Unit:mm(inch) |

(4)Leader and Blank portion



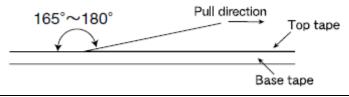






(6) Top Tape Strength

The top The top tape requires a peel-off force of 0.1 to 1.2N in the direction of the arrow as illustrated below.





METAL CORE WIRE-WOUND CHIP POWER INDUCTORS (MCOIL[™] MA SERIES / MCOIL[™] MA-H SERIES)

RELIABILITY DATA

| 1. Operating Tempe | 1. Operating Temperature Range | | | | | |
|-----------------------------|--------------------------------|---------------------------|--|--|--|--|
| Specified Value | MA series | $-40 \sim +105^{\circ}$ C | | | | |
| | MA-H series | −40~+125°C | | | | |
| Test Methods and Remarks | Including self-generated heat | | | | | |

| 2. Storage Tempera | 2. Storage Temperature Range | | | | |
|-----------------------------|--|-----------|--|--|--|
| Specified Value | MA series | -40~+85°C | | | |
| | MA-H series | | | | |
| Test Methods and Remarks | 0 to 40° C for the product with taping. | | | | |

| 3. Rated current | | | | |
|------------------|-------------|--------------------------------|--|--|
| Specified Value | MA series | | | |
| | MA-H series | Within the specified tolerance | | |

| 4. Inductance | | | | |
|-----------------------------|--|-------------------------------|---------------------------------|--|
| Crasified Malue | MA series | | Weblin Abor and a Condition and | |
| Specified Value | MA-H series | | Within the specified tolerance | |
| Test Methods and Remarks | Measuring equipment Measuring frequency | : LCR Meter(HP 4 : 2MHz、1V | 285A or equivalent) | |

| 5. DC Resistance | 5. DC Resistance | | | | |
|-----------------------------|--------------------------------------|--------------------------------|--|--|--|
| Specified Value | MA series | Within the specified tolerance | | | |
| | MA-H series | within the specified tolerance | | | |
| Test Methods and Remarks | Measuring equipment : DC ohmmeter(HI | OKI 3227 or equivalent) | | | |

| 6. Self resonance frequency | | |
|-----------------------------|-------------|---|
| Specified Value | MA series | _ |
| | MA-H series | |

| 7. Temperature characteristic | | | |
|-------------------------------|---|---------------------------------------|--|
| Specified Value | MA series | Industance change, Within ± 150 | |
| Specified Value | MA-H series | Inductance change : Within $\pm 15\%$ | |
| Test Methods and Remarks | Measurement of inductance shall be taken at temperature range within $-40^{\circ}C \sim +85^{\circ}C$. With reference to inductance value at $+20^{\circ}C$., change rate shall be calculated. | | |

| 8. Resistance to fle | xure of substrate | | |
|-----------------------------|-------------------|--|----------------------|
| Crassifierd Malue | MA series | | |
| Specified Value | MA-H series | | - No damage |
| Test Methods and Remarks | l | | 0 mm Force Rod 10 20 |

| 9. Insulation resistance : between wires | | |
|--|-------------|--|
| Specified Value | MA series | |
| | MA-H series | |

| 10. Insulation resistance : between wire and core | | | |
|---|-------------|--|--|
| Specified Value | MA series | | |
| | MA-H series | | |

| 11. Withstanding voltage : between wire and core | | |
|--|-------------|--|
| Specified Value | MA series | |
| | MA-H series | |

| 12. Adhesion of terr | 12. Adhesion of terminal electrode | | | | |
|----------------------|------------------------------------|--------------------|-------------------------|--|--|
| Specified Value | MA series | | | | |
| Specified value | MA-H series | | No abnormality. | | |
| | The test samples shall be s | oldered to the tes | st board by the reflow. | | |
| Test Methods and | nd Applied force : 10N to X and | | Y directions. | | |
| Remarks | Duration | | | | |
| | Solder cream thickness : 0.12mm. | | | | |

| 13. Resistance to vi | to vibration | | | | |
|-----------------------------|--|---------------------------------------|--|--|--|
| Specified Value | MA series | | Inductance change : Within $\pm 10\%$ No significant abnormality in appearance. | | |
| Specified Value | MA-H series | | | | |
| | The test samples shall be Then it shall be submitted Frequency Range | | | | |
| T . M | Total Amplitude | 1.5mm (May not | exceed acceleration 196m/s²) | | |
| Test Methods and Remarks | Sweeping Method | 10Hz to 55Hz to 10Hz for 1min. | | | |
| Remarks | Time X Z | For 2 hours on each X, Y, and Z axis. | | | |
| | Recovery : At least 2hrs o | f recovery under t | the standard condition after the test, followed by the measurement within 48hrs. | | |

| 14. Solderability | | | |
|-----------------------------|---|----------------|---|
| Specified Value | MA series | | At least 90% of surface of terminal electrode is covered by new solder. |
| | MA-H series | | |
| T . M .: 1 | The test samples shall be dipped in flux, and then immersed in molten solder as shown in below table. Flux : Methanol solution containing rosin 25%. | | |
| Test Methods and Remarks | Solder Temperature | 245±5°C | |
| | Time | 5 ± 0.5 sec. | |
| | XImmersion depth : All sides of mounting ter | | minal shall be immersed. |

| 15. Resistance to soldering heat | | | | |
|----------------------------------|---|--|--|--|
| Specified Value | MA series | Inductance change : Within $\pm 10\%$ No significant abnormality in appearance. | | |
| Specified value | MA-H series | | | |
| | The test sample shall be exposed to reflow ov | en at 230°C for 40 seconds, with peak temperature at $260+0/-5$ °C for 5 seconds, 3 times. | | |
| Test Methods and | Test board material : Glass epoxy-resin | | | |
| Remarks | Test board thickness : 1.0mm | | | |
| | Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs. | | | |



| 16. Thermal shock | k | | | | |
|-------------------|---|------------------|---------------------------|---|--|
| Specified Value | MA series | | Inductance change | : Within $\pm 10\%$ | |
| | MA-H series | | No significant abn | ormality in appearance. | |
| | | | low table in sequence. Th | r. The test samples shall be placed at specified temperature for specified e temperature cycle shall be repeated 100 cycles. | |
| Test Methods and | 1 | -40±3 | 30±3 | | |
| Remarks | 2 | Room temperature | Within 3 | | |
| | 3 | $+85\pm2$ | 30 ± 3 | | |
| | 4 | Room temperature | Within 3 | | |
| | Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs. | | | | |

| 17. Damp heat | eat | | | | |
|------------------|---|----------------|---|--|--|
| Specified Value | MA series | | Inductance change : Within $\pm 10\%$ | | |
| Specified value | MA-H series | | No significant abnormality in appearance. | | |
| Test Methods and | The test samples shall be soldered to the test board by the reflow. The test samples shall be placed in thermostatic oven set at specified temperature and humidity as shown in below table. | | | | |
| Remarks | Temperature | 60±2°C | | | |
| Remarks | Humidity | 90~95%RH | | | |
| | Time | 500+24/-0 hour | | | |
| | Recovery : At least 2hrs of recovery under the standard condition after the test, followed by the measurement within 48hrs. | | | | |

| 18. Loading under damp heat | | | |
|-----------------------------|--|--|--|
| Specified Value | MA series | | Inductance change : Within $\pm 10\%$ |
| | MA-H series | | No significant abnormality in appearance. |
| Test Methods and Remarks | The test samples s continuously as show Temperature Humidity Applied current Time | wn in below table. $60\pm 2^{\circ}C$ $90\sim 95\%$ RH Rated current $500\pm 24/-0$ hour | st board by the reflow. nostatic oven set at specified temperature and humidity and applied the rated current |

| 19. Low temperatur | 19. Low temperature life test | | | |
|--------------------|-------------------------------|-----------------------------|---|--|
| Specified Value | MA series | | Inductance change : Within $\pm 10\%$ | |
| Specified value | MA-H series | | No significant abnormality in appearance. | |
| | The test samples sha | all be soldered to the test | board by the reflow. After that, the test samples shall be placed at test conditions as shown | |
| Test Methods and | in below table. | | | |
| Remarks | Temperature | $-40\pm2^{\circ}C$ | | |
| | Time | 500+24/-0 hour | | |
| | Recovery : At least 2 | hrs of recovery under th | e standard condition after the test, followed by the measurement within 48hrs. | |

| 20. High temperatur | 20. High temperature life test | | | |
|---------------------|--------------------------------|-----------------------------|---|--|
| Specified Value | MA series | | Inductance change : Within $\pm 10\%$ | |
| Specified value | MA-H series | | No significant abnormality in appearance. | |
| | The test samples sha | all be soldered to the test | board by the reflow. After that, the test samples shall be placed at test conditions as shown | |
| Test Methods and | in below table. | | | |
| Remarks | Temperature | 85±2°C | | |
| | Time | 500+24/-0 hour | | |
| | Recovery : At least 2 | 2hrs of recovery under th | e standard condition after the test, followed by the measurement within 48hrs. | |

| 21. Loading at high temperature life test | | |
|---|-------------|---|
| Specified Value | MA series | _ |
| | MA-H series | |



| 22. Standard condition | | |
|------------------------|-------------|---|
| Specified Value | MA series | Standard test condition : Unless otherwise specified, temperature is $20\pm15^\circ$ C and $65\pm20\%$ of relative humidity. |
| | MA-H series | When there is any question concerning measurement result: In order to provide correlation data, the test shall be condition of $20\pm2^{\circ}C$ of temperature, $65\pm5\%$ relative humidity. Inductance is in accordance with our measured value. |
| | | |

METAL CORE WIRE-WOUND CHIP POWER INDUCTORS (MCOIL[™] MA SERIES / MCOIL[™] MA-H SERIES)

PRECAUTIONS

| 1. Circuit Design | |
|-------------------|---|
| Precautions | Operating environment The products described in this specification are intended for use in general electronic equipment,(office supply equipment, telecommunications systems, measuring equipment, and household equipment). They are not intended for use in mission-critical equipment or systems requiring special quality and high reliability (traffic systems, safety equipment, aerospace systems, nuclear control systems and medical equipment including life-support systems,) where product failure might result in loss of life, injury or damage. For such uses, contact TAIYO YUDEN Sales Department in advance. |

| 2. PCB Design | |
|--------------------------|---|
| Precautions | ◆Land pattern design 1. Please refer to a recommended land pattern. |
| Technical considerations | Land pattern design Surface Mounting Mounting and soldering conditions should be checked beforehand. Applicable soldering process to this products is reflow soldering only. |

| 3. Considerations | 3. Considerations for automatic placement | | |
|--------------------------|--|--|--|
| Precautions | Adjustment of mounting machine 1. Excessive impact load should not be imposed on the products when mounting onto the PC boards. 2. Mounting and soldering conditions should be checked beforehand. | | |
| Technical considerations | Adjustment of mounting machine 1. When installing products, care should be taken not to apply distortion stress as it may deform the products. | | |

| 4. Soldering | |
|-----------------------------|--|
| Precautions | Reflow soldering Please contact any of our offices for a reflow soldering, and refer to the recommended condition specified. The product shall be used reflow soldering only. Please do not add any stress to a product until it returns in normal temperature after reflow soldering. Lead free soldering When using products with lead free soldering, we request to use them after confirming adhesion, temperature of resistance to soldering heat, soldering etc sufficiently. |
| Technical considerations | Reflow soldering 1. If products are used beyond the range of the recommended conditions, heat stresses may deform the products, and consequently degrade the reliability of the products. Recommended reflow condition (Pb free solder) 300 300 100 150~180 100 90 ± 30 sec 100 90 ± 30 sec Heating Time [sec] |

| 5. Cleaning | 5. Cleaning | | |
|--------------------------|--|--|--|
| Precautions | ◆Cleaning conditions 1. Washing by supersonic waves shall be avoided. | | |
| Technical considerations | Cleaning conditions 1. If washed by supersonic waves, the products might be broken. | | |



| 6. Handling | |
|-----------------------------|---|
| Precautions | Handling Keep the product away from all magnets and magnetic objects. Breakaway PC boards (splitting along perforations) When splitting the PC board after mounting product, care should be taken not to give any stresses of deflection or twisting to the board. Board separation should not be done manually, but by using the appropriate devices. Mechanical considerations Please do not give the product any excessive mechanical shocks. Please do not add any shock and power to a product in transportation. Pick-up pressure Please do not push to add any pressure to a winding part. Please do not give any shock and push into a ferrite core exposure part. Packing Please avoid accumulation of a packing box as much as possible. |
| Technical considerations | Handling There is a case that a characteristic varies with magnetic influence. Breakaway PC boards (splitting along perforations) The position of the product on PCBs shall be carefully considered to minimize the stress caused from splitting of the PCBs. Mechanical considerations There is a case to be damaged by a mechanical shock. There is a case to be broken by the handling in transportation. Pick-up pressure Damage and a characteristic can vary with an excessive shock or stress. Packing If packing boxes are accumulated, that could cause a deformation on packing tapes or a damage on the products. |

| 7. Storage condi | tions |
|--------------------------|---|
| Precautions | Storage To maintain the solderability of terminal electrodes and to keep the packing material in good condition, temperature and humidity in the storage area should be controlled. Recommended conditions |
| Technical considerations | Storage 1. Under a high temperature and humidity environment, problems such as reduced solderability caused by oxidation of terminal electrodes and deterioration of taping/packaging materials may take place. |

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Mouser Electronics

Authorized Distributor

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Taiyo Yuden:

| MAKK2520H2R2M | MAKK2520HR47M | MAKK2520HR33M | MAMK2520HR47M | MAKK2016HR24M |
|---------------|---------------|---------------|---------------|---------------|
| MAKK2016HR68M | MAKK2016H1R0M | MAKK2016H1R5M | MAKK2016HR33M | MAKK2016HR47M |
| MAMK2520H1R0M | MAKK2520H1R0M | MAMK2520H2R2M | MAKK2520HR68M | MAMK2520H1R5M |
| MAMK2520HR68M | MAMK2520HR33M | MAKK2520H1R5M | MAKK2520HR22M | MAMK2520HR22M |
| MAKK2520H100M | MAKK2016HR22M | | | |